

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t3032ede-12#pbf

(Engineering Calculation)

DFN 4mm X 3mm Exp. Pad

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**TOTAL MASS (g) : 0.030484**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000885	1000000	29031.8457031		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.013131	974800.0625	430753.84375		
		Iron (Fe)	7439-89-6	0.000317	23500	10398.9775391		
		Phosphorus (P)	7723-14-0	0.000011	850	360.847808838		
		Zinc (Zn)	7440-66-6	0.000011	850	360.847808838		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.013470</b>	<b>1000000</b>	<b>441874.5</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000626	1000000	20527.9335938		
		<b>External Plating Total:</b>				<b>0.000626</b>	<b>1000000</b>	<b>20527.9335938</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000302	1000000	9906.91210938		
<b>Internal Plating Total:</b>				<b>0.000302</b>	<b>1000000</b>	<b>9906.91210938</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000536	750000	17583.1289062		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000179	250000	5871.97753906		
<b>Die Attach Total:</b>				<b>0.000715</b>	<b>1000000</b>	<b>23455.1054688</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.001876	130000	61540.9492188		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.012410	860000	407101.90625		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000144	10000	4723.82617188		
		<b>Encapsulation Total:</b>				<b>0.014430</b>	<b>1000000</b>	<b>473366.71875</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000056	1000000	1837.04333496		
					<b>TOTAL MASS (g) :</b>	<b>0.030484</b>		